



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Small et al.  
Title: Compositions for Chemical Mechanical Planarization of Copper  
Application No.: 10/017,934 Filing Date: December 12, 2001  
Examiner: Umez Eronini, Lynette T. Group Art Unit: 1765  
Docket No.: CHEM.001US0 Conf. No.: 1435

**Certificate of Mailing Under 37 CFR 1.8**

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450,  
on 9/22/04

Julieen Bowe  
Signature

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

This is in response to a final office action mailed April 22, 2004 and setting a shortened statutory period for response that expires on July 22, 2004. Entry and consideration of this response are earnestly requested, as it shows that the application is in condition for allowance as to at least one claim that was presented previously and is amended only cosmetically herein, based on the Examiner's indication of allowable subject matter in both the first and the final office actions, as well as the new claims depending therefrom, and as it addresses rejections that were newly presented in the final office action. The response is believed to put the application in condition for allowance or in better condition for consideration on appeal. In view of the following amendment and remarks, reconsideration is respectfully requested.

06/29/2004 AWONDAF1 00000111 10017934

01 FC:1202

396.00 OP

CHEM.001US0

- 1 -

Serial No.: 10/017,934